

FDFS2P102

Integrated P-Channel MOSFET and Schottky Diode

General Description

The FDFS2P102 combines the exceptional performance of Fairchild's high cell density MOSFET with a very low forward voltage drop Schottky barrier rectifier in an SO-8 package.

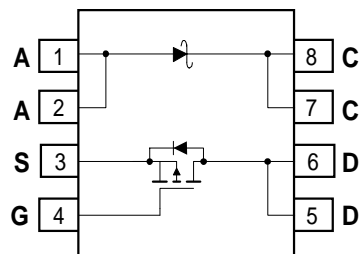
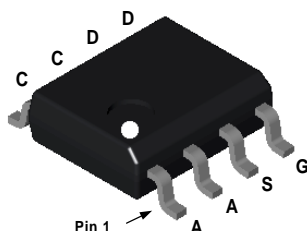
This device is designed specifically as a single package solution for DC to DC converters. It features a fast switching, low gate charge MOSFET with very low on-state resistance. The independently connected Schottky diode allows its use in a variety of DC/DC converter topologies.

Applications

- DC/DC converters
- Load Switch
- Motor Drives

Features

- -3.3 A , -20 V . $R_{DS(ON)} = 0.125\ \Omega$ @ $V_{GS} = -10\text{ V}$
 $R_{DS(ON)} = 0.200\ \Omega$ @ $V_{GS} = -4.5\text{ V}$.
- $V_F < 0.39\text{ V}$ @ 1 A ($T_J = 125^\circ\text{C}$).
 $V_F < 0.47\text{ V}$ @ 1 A .
 $V_F < 0.58\text{ V}$ @ 2 A .
- Schottky and MOSFET incorporated into single power surface mount SO-8 package.
- Electrically independent Schottky and MOSFET pinout for design flexibility.



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	-20	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous (Note 1a)	-3.3	A
	- Pulsed	-20	
P_D	Power Dissipation for Dual Operation	2	W
	Power Dissipation for Single Operation (Note 1a)	1.6	
	(Note 1b)	1	
	(Note 1c)	0.9	
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Schottky Diode Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

V_{RRM}	Repetitive Peak Reverse Voltage	20	V
I_O	Average Forward Current (Note 1a)	1	A

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDFS2P102	FDFS2P102	13	12mm	2500 units

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16\text{ V},$ $V_{GS} = 0\text{ V}$			-1	μA
		$T_J = 55^\circ\text{C}$			-10	
I_{GSSF}	Gate-Body Forward Leakage	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA
I_{GSSR}	Gate-Body Reverse Leakage	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$			-100	nA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-1	-1.4	-2	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -3.3\text{ A}$		0.100	0.125	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -2.5\text{ A}$		0.167	0.2	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = -10\text{ V}, V_{DS} = -5\text{ V}$	-10			A
g_{FS}	Forward Transconductance	$V_{DS} = -10\text{ V}, I_D = -3.3\text{ A}$		5		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		270		pF
C_{oss}	Output Capacitance			150		pF
C_{rss}	Reverse Transfer Capacitance			45		pF

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -15\text{ V}, I_D = -1\text{ A},$ $V_{GS} = -10\text{ V}, R_{GEN} = 6\text{ }\Omega$		8	16	ns
t_r	Turn-On Rise Time			7	14	ns
$t_{d(off)}$	Turn-Off Delay Time			17	27	ns
t_f	Turn-Off Fall Time			10	1.8	ns
Q_g	Total Gate Charge	$V_{DS} = -5\text{ V}, I_D = -3.3\text{ A},$ $V_{GS} = -10\text{ V},$		7	10	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current					-1.3	A	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -1.3 A	(Note 2)			-0.8	-1.2	V

Schottky Diode Characteristics

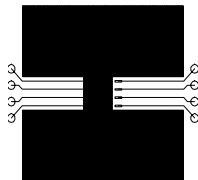
I_R	Reverse Leakage	$V_R = 20\text{ V}$	$T_J = 25^\circ\text{C}$		250	μA
			$T_J = 125^\circ\text{C}$		18	mA
V_F	Forward Voltage	$I_F = 1\text{ A}$	$T_J = 25^\circ\text{C}$		0.47	V
			$T_J = 125^\circ\text{C}$		0.39	
		$I_F = 2\text{ A}$	$T_J = 25^\circ\text{C}$		0.58	
			$T_J = 125^\circ\text{C}$		0.53	

Thermal Characteristics

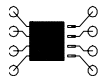
R_{JA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	
R_{JC}	Thermal Resistance, Junction-to-Case	(Note 1)	40	

Notes:

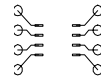
1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50°C/W when mounted on a 1 in² pad of 2 oz. copper.



b) 105°C/W when mounted on a 0.04 in² pad of 2 oz. copper.



c) 125°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$

Typical Characteristics

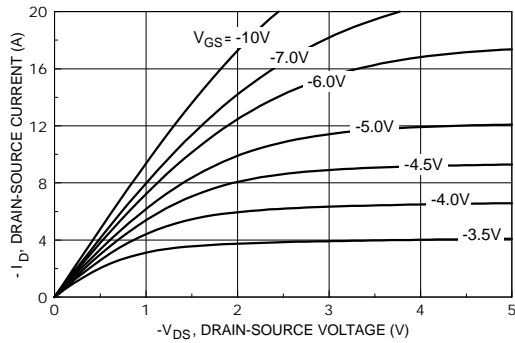


Figure 1. On-Region Characteristics.

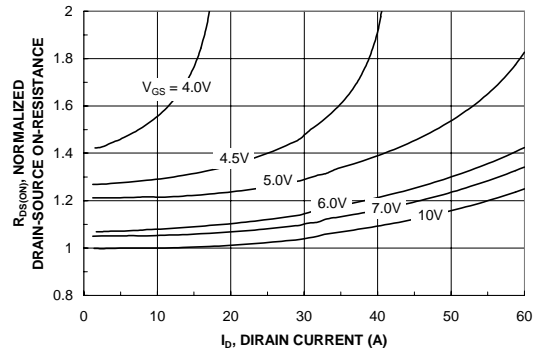


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

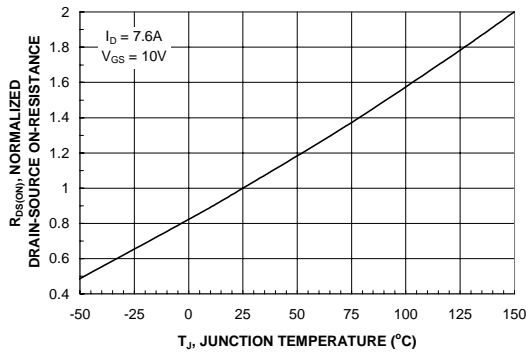


Figure 3. On-Resistance Variation with Temperature.

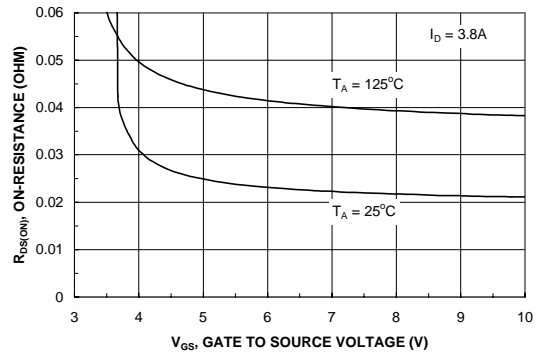


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

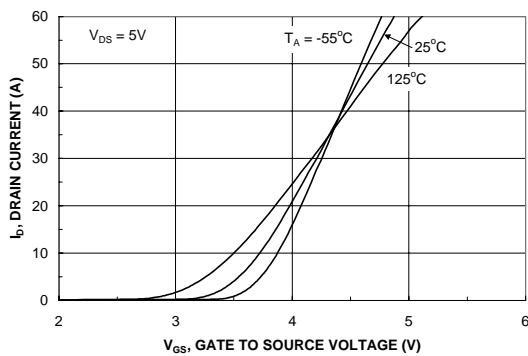


Figure 5. Transfer Characteristics.

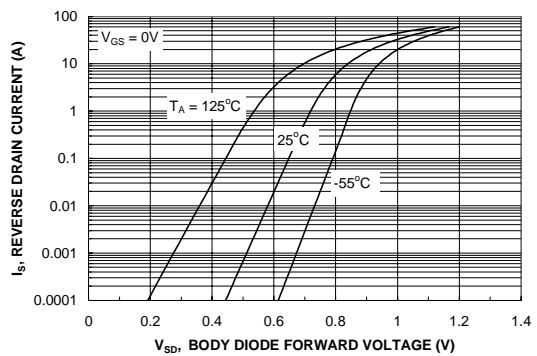


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)

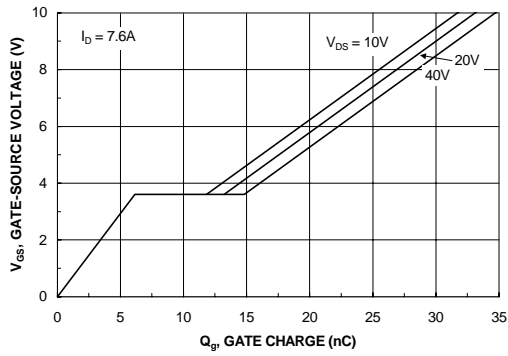


Figure 7. Gate-Charge Characteristics.

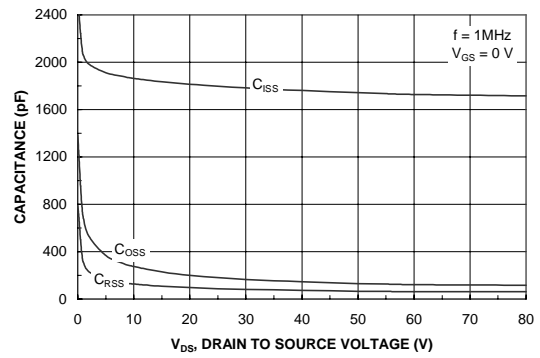


Figure 8. Capacitance Characteristics.

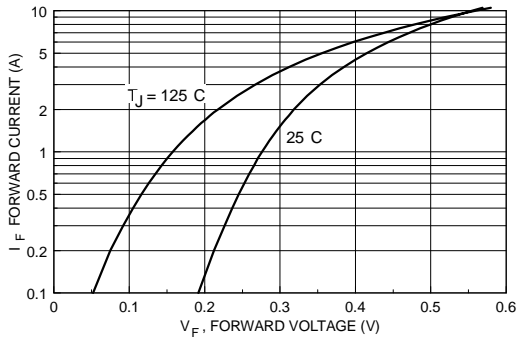


Figure 9. Schottky Diode Forward Voltage.

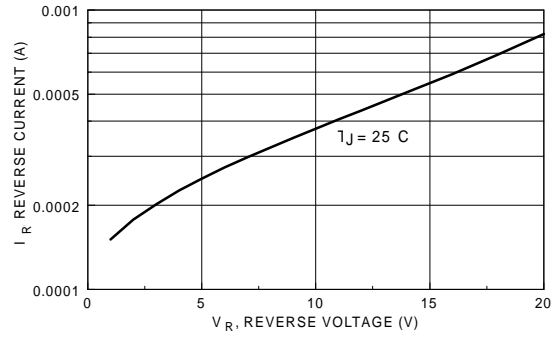


Figure 10. Schottky Diode Reverse Current.

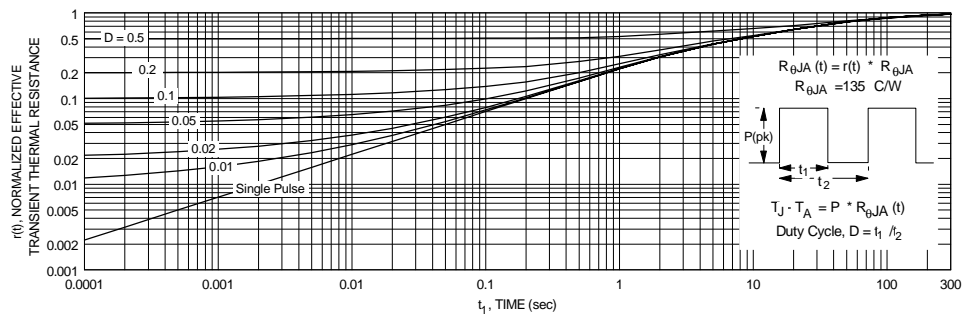


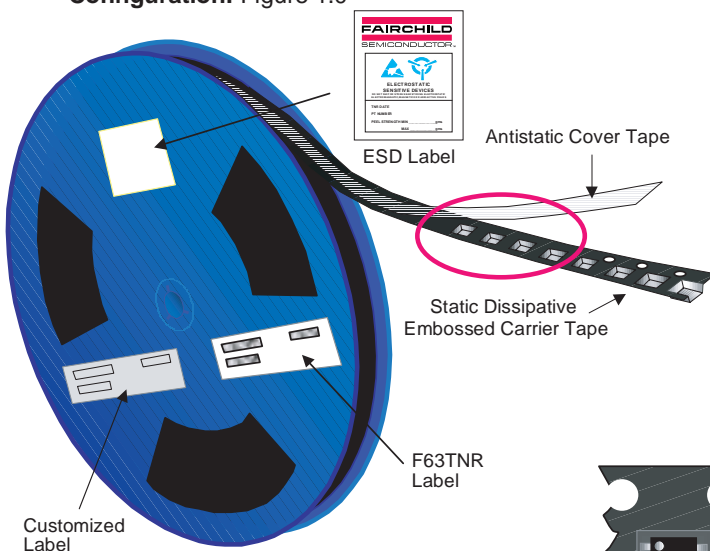
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.
Transient thermal response will change depending on the circuit board design.

SOIC-8 Tape and Reel Data



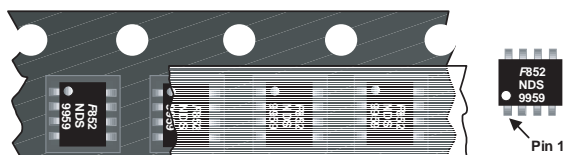
SOIC(8lds) Packaging Configuration: Figure 1.0



Packaging Description:

SOIC-8 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 330cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 500 units per 7" or 177cm diameter reel. This and some other options are further described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a standard intermediate box (illustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains two reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

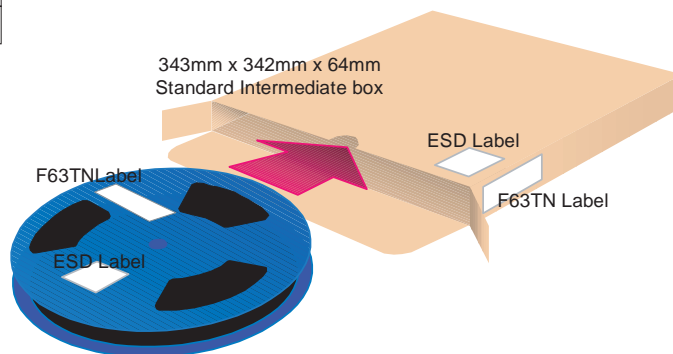


SOIC-8 Unit Orientation

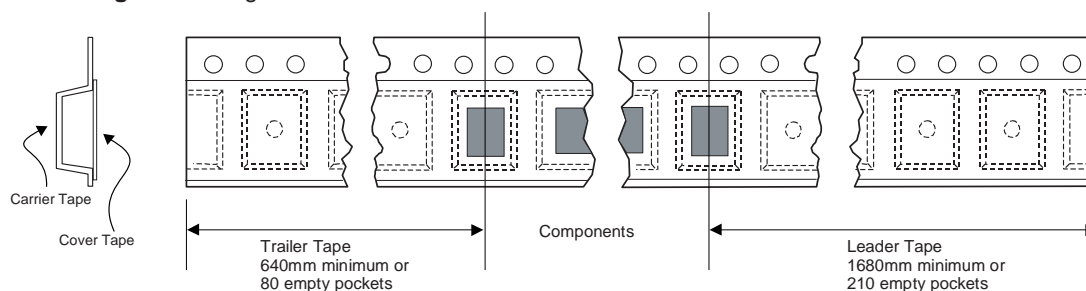
SOIC (8lds) Packaging Information				
Packaging Option	Standard (no flow code)	L86Z	F011	D84Z
Packaging type	TNR	Rail/Tube	TNR	TNR
Qty per Reel/Tube/Bag	2,500	95	4,000	500
Reel Size	13" Dia	-	13" Dia	7" Dia
Box Dimension (mm)	343x64x343	530x130x83	343x64x343	184x187x47
Max qty per Box	5,000	30,000	8,000	1,000
Weight per unit (gm)	0.0774	0.0774	0.0774	0.0774
Weight per Reel (kg)	0.6060	-	0.9696	0.1182
Note/Comments				

F63TNR Label sample

LOT: CBVK741B019	QTY: 2500
FSID: FDS9953A	SPEC:
D/C1: D9842	QTY1: QTY2:
D/C2:	SPEC REV: CPN:
	N/F: F (F63TNR)3

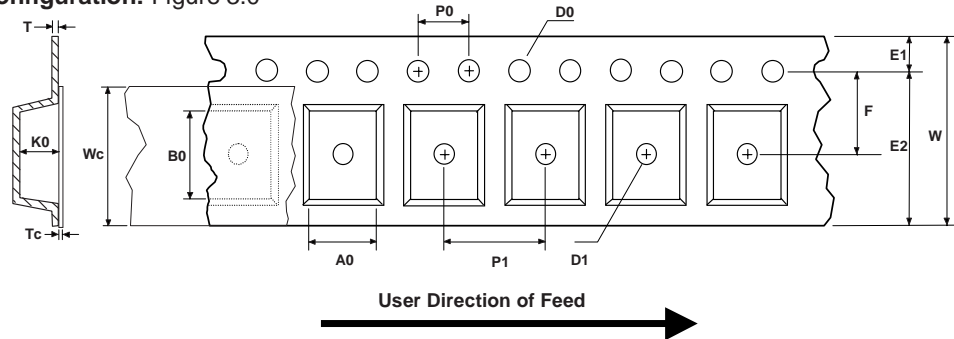


SOIC(8lds) Tape Leader and Trailer Configuration: Figure 2.0



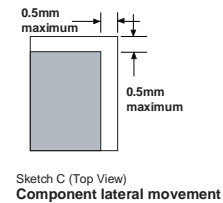
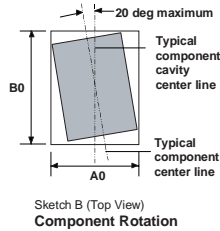
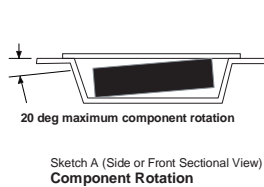
SOIC-8 Tape and Reel Data, continued

SOIC(8lds) Embossed Carrier Tape Configuration: Figure 3.0

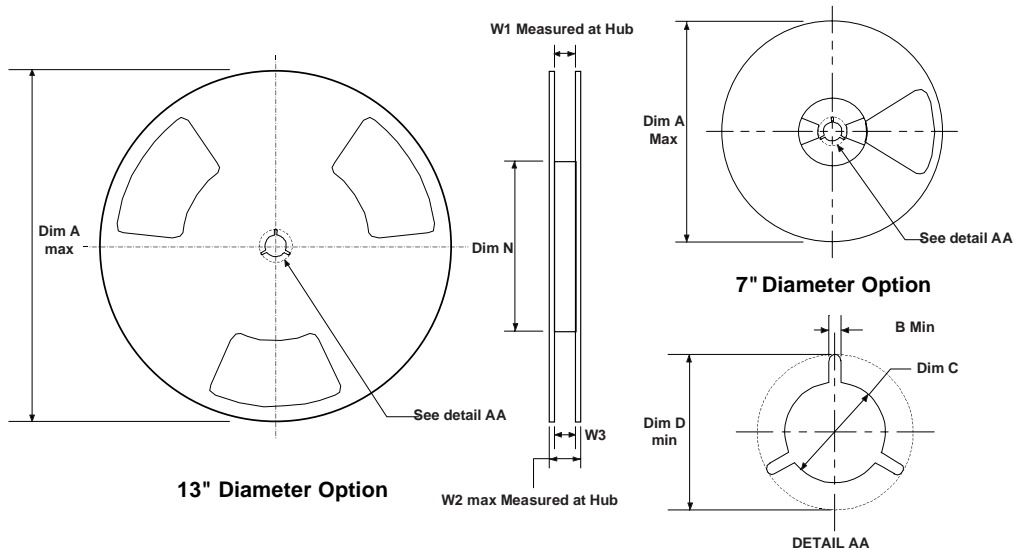


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOIC(8lds) (12mm)	6.50 +/-0.10	5.30 +/-0.10	12.0 +/-0.3	1.55 +/-0.05	1.60 +/-0.10	1.75 +/-0.10	10.25 min	5.50 +/-0.05	8.0 +/-0.1	4.0 +/-0.1	2.1 +/-0.10	0.450 +/- 0.150	9.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



SOIC(8lds) Reel Configuration: Figure 4.0

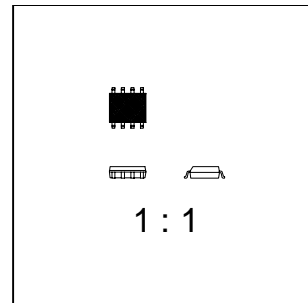
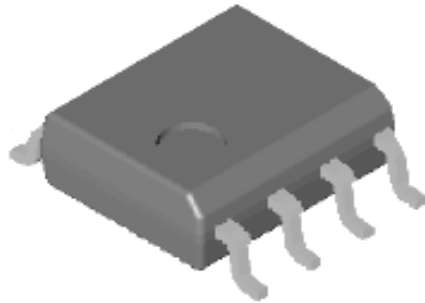


Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
12mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4
12mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	7.00 178	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4

SOIC-8 Package Dimensions



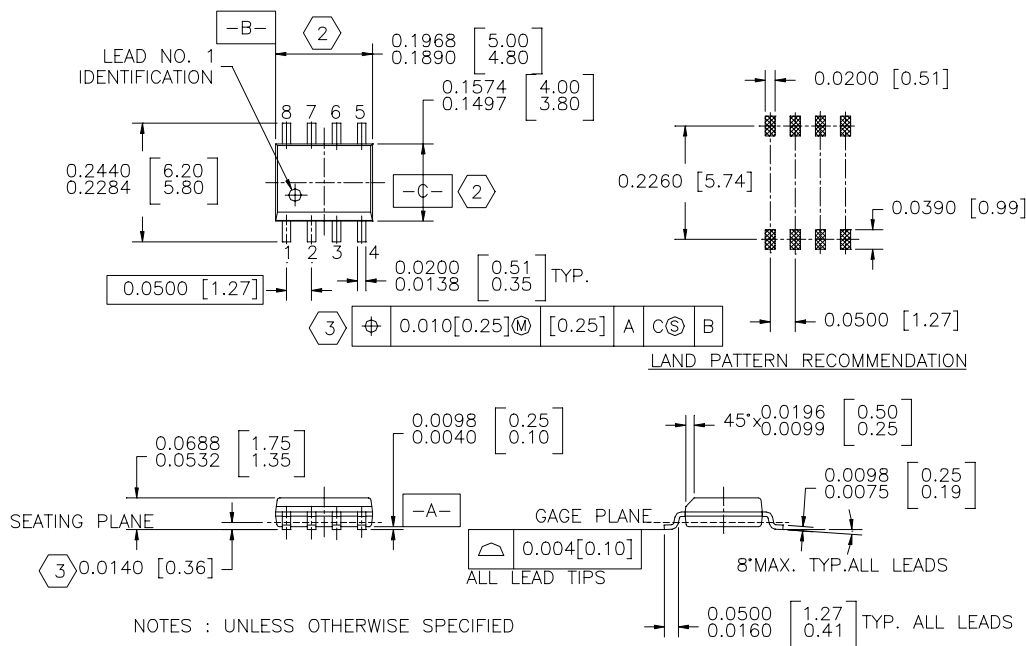
SOIC-8 (FS PKG Code S1)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.0774



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CROSSVOLT [™]	HiSeC [™]	Quiet Series [™]	
DOVE [™]	ISOPANAR [™]	SuperSOT [™] -3	
E ² CMOS [™]	MICROWIRE [™]	SuperSOT [™] -6	
EnSigna [™]	OPTOLOGIC [™]	SuperSOT [™] -8	
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PRODUCT STATUS DEFINITIONS

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Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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